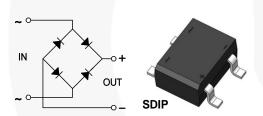


October 2014

DF005S2 - DF10S2 Bridge Rectifier

Features

- Maximum Surge Rating: $I_{FSM} = 85 \text{ A}$ $I^2t = 30 \text{ A}^2\text{Sec}$
- Optimized V_F: Typical 0.93 V at 2 A, 25°C
- · DF10S Socket Compatible
- Glass Passivated Junctions
- Space Saving
- Lead Free in Comply with EU RoHS 2002/95/EU Directives
- Green Molding Compound: IEC61249 Halogen Free
- · Qualified with IR Reflow and Wave Soldering



Description

With the ever-pressing need to improve power supply efficiency, improve surge rating, improve reliability, and reduce size, the DFxS2 family sets a new standard in performance.

The new design offers an improved surge rating of 85 A. This is especially important when striving to improve reliability and increase efficiency. High efficiency designs strive to reduce circuit resistance, which, unfortunately can result in increased inrush surge. As such higher surge current ratings can be required to maintain or improve reliability.

The design also offers improved efficiency by achieving a 2 A V_F of 1.1 V maximum at 25°C. This lower V_F also supports cooler and more efficient operation.

Finally, the DFxS2 achieves all this in a SDIP surface mount form factor, reducing board space and volumetric requirements vs. competitive devices.

Ordering Information

| Part Number | Top Mark | Package | Packing Method | |
|-------------|----------|---------|----------------|--|
| DF005S2 | DF005S2 | SDIP 4L | Tape and Reel | |
| DF01S2 | DF01S2 | SDIP 4L | Tape and Reel | |
| DF02S2 | DF02S2 | SDIP 4L | Tape and Reel | |
| DF04S2 | DF04S2 | SDIP 4L | Tape and Reel | |
| DF06S2 | DF06S2 | SDIP 4L | Tape and Reel | |
| DF08S2 | DF08S2 | SDIP 4L | Tape and Reel | |
| DF10S2 | DF10S2 | SDIP 4L | Tape and Reel | |

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Value | | | | | | Unit | |
|--------------------|---|--------------------------------|--------|--------|------------|--------|--------|--------|------|
| | | DF005S2 | DF01S2 | DF02S2 | DF04S2 | DF06S2 | DF08S2 | DF10S2 | Uill |
| V _{RRM} | Maximum Recurrent Peak Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| V _{RMS} | Maximum RMS Bridge Input Voltage | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| V _{DC} | Maximum DC Blocking Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| I _{F(AV)} | Maximum Average Forward Current T _A = 40°C | | | | 2.0 | | | | А |
| I _{FSM} | Peak Forward Surge Current 8.3 ms Single Half-Sine Wave Superimposed on Rated Load(JEDEC Method) | ngle Half-Sine erimposed on | | 85 | | | | А | |
| T _{STG} | Storage Temperature Range | | | -{ | 55 to +150 |) | | | °C |
| TJ | Operating Junction Temperature Range | | | -{ | 55 to +150 |) | | | °C |

Thermal Characteristics(1)

| Symbol | Parameter | Conditions | Max. | Unit |
|------------------|--|---|------|------|
| | | Single-Die Measurement (Maximum Land Pattern: 13 x 13 mm) | 60 | |
| R _{θJA} | Junction to Ambient | Multi-Die Measurement (Maximum Land Pattern: 13 x 13 mm) | 50 | °C/W |
| | | Multi-Die Measurement (Minimum Land Pattern: 1.3 x 1.5 mm) | 100 | |
| ΨJL | Thermal Characterization Parameter, Junction to Lead | Single-Die Measurement (Maximum and Minimum Land Pattern) | 25 | °C/W |

Note:

1. The thermal resistances ($R_{\theta JA} \& \psi_{JL}$) are characterized with the device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm.

Heating effect from adjacent dice is considered and only two dices are powered at the same time.

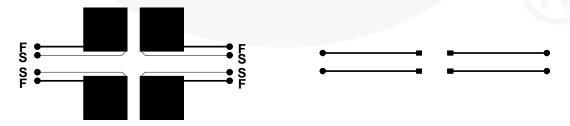


Figure 1. Maximum Pads of 2 oz Copper

Figure 2. Minimum Pads of 2 oz Copper

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|------------------|---|--|------|------|------|------------------|
| V _F | Forward Voltage Drop per Bridge Element | I _F = 2.0 A | | | 1.1 | V |
| | DC Reverse Current | $T_J = 25^{\circ}C$ | | | 3 | μА |
| | at Rated DC Blocking Voltage | T _J = 125°C | | | 500 | |
| l ² t | Rating for Fusing (t < 8.3 ms) | | | | 30 | A ² S |
| CJ | Junction Capacitance | V _R = 4.0 V, f = 1.0 MHz | | 23 | | pF |

Typical Performance Characteristics

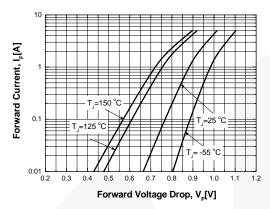


Figure 3. Typical Instantaneous Forward Characteristics

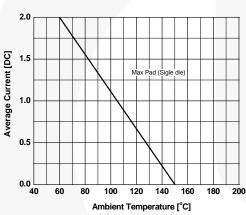


Figure 5. Maximum Average Current vs.
Ambient Temperature

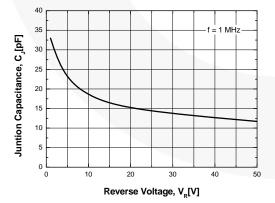


Figure 7. Typical Junction Capacitance

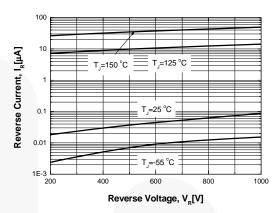


Figure 4. Typical Reverse Characteristics

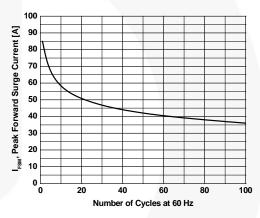
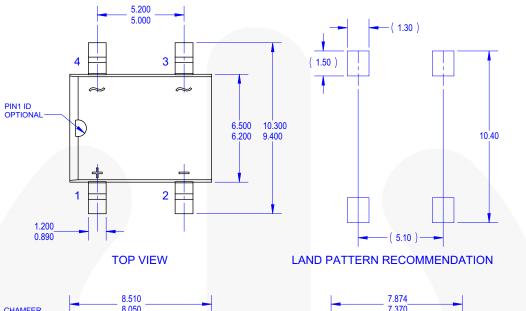
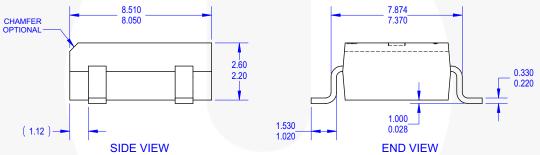


Figure 6. Peak Forward Surge Current vs.

Number of Cycles at 60Hz

Physical Dimensions





NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY REFERENCE STANDARD.
 B. ALL DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
 G. DRAWING FILE NAME: MKT-SDIP04AREV4.

Figure 8. 4-LEAD, SDIP, 6.5 MM WIDE





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